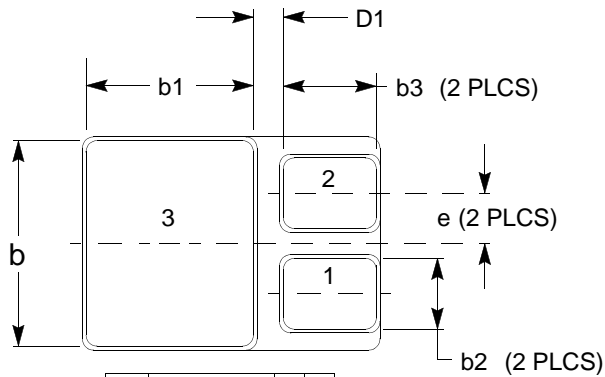
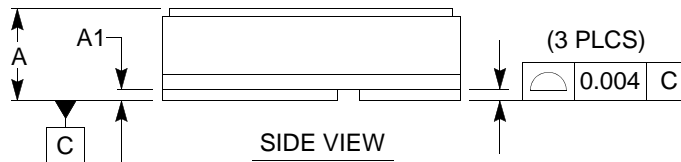
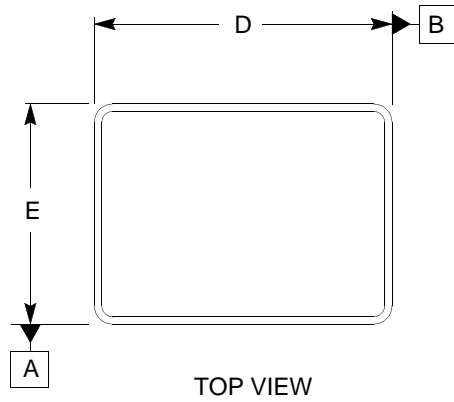


Ceramic Leadless Chip Carrier Packages (CLCC)



- 1 - GATE
- 2 - SOURCE
- 3 - DRAIN

J3.A

3 PAD HERMATIC SMD.5 PACKAGE
CERAMIC BOTTOM TERMINAL CHIP CARRIER

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.110	0.124	2.79	3.15	3
A1	0.010	0.020	0.25	0.51	-
b	0.281	0.291	7.13	7.39	-
b1	0.220	0.230	5.58	5.84	-
b2	0.090	0.100	2.28	2.54	-
b3	0.115	0.125	2.92	3.18	-
D	0.395	0.405	10.03	10.28	-
D1	0.030	-	0.76	-	-
E	0.291	0.301	7.39	7.64	-
e	0.075 BSC		1.91 BSC		-

Rev. 1 4/03

NOTES:

1. Controlling dimensions are in inches (mm for reference only).
2. Dimensioning and tolerance per ANSI Y14.5M - 1982
3. The maximum "A" dimension is package height before being solder dipped.
4. Patterned after MIL-STD-1835 CBCC1-N3 (C-B1) Note: Not meeting the Mil-Std "A" min. dimension of 0.112